

To all our customers

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Renesas Technology Corp.  
Customer Support Dept.  
April 1, 2003

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Keep safety first in your circuit designs!

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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# HSS104

Silicon Epitaxial Planar Diode for High Speed Switching

# RENESAS

ADE-208-178B (Z)

Rev.2  
Oct. 2000

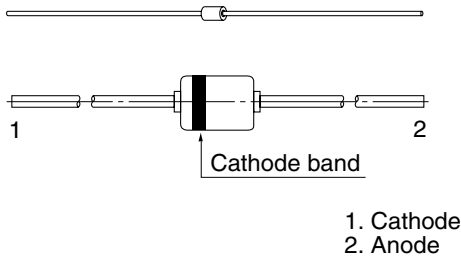
## Features

- Short reverse recovery time and forward recovery time.
- Suitable for 5 mm pitch high speed automatically insertion.
- Small glass package (MHD) enables easy mounting and high reliability.

## Ordering Information

Type No.	Cathode band	Package Code
HSS104	Blue	MHD

## Pin Arrangement



## Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Peak reverse voltage	$V_{RM}$	40	V
Reverse voltage	$V_R$	35	V
Average rectified current	$I_O$	110	mA
Peak forward current	$I_{FM}$	300	mA
Non-Repetitive peak forward surge current	$I_{FSM}^*$	0.4	A
Power dissipation	Pd	300	mW
Junction temperature	Tj	175	°C
Storage temperature	Tstg	-65 to +175	°C

Note: Within 1s forward surge current.

## Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	$V_F$	—	—	1.2	V	$I_F = 100 \text{ mA}$
Reverse current	$I_R$	—	—	0.5	$\mu\text{A}$	$V_R = 35 \text{ V}$
Capacitance	C	—	—	3.0	pF	$V_R = 0.5 \text{ V}, f = 1 \text{ MHz}$
Reverse recovery time	$t_{rr}$	—	—	3.0	ns	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}, R_L = 50 \Omega$

Main Characteristic

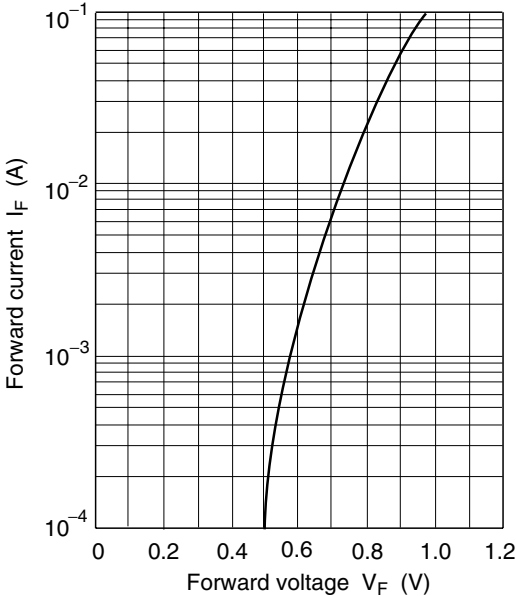


Fig.1 Forward current Vs. Forward voltage

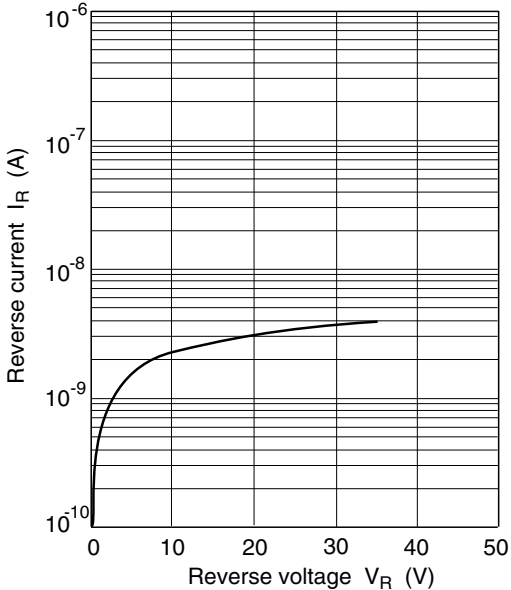


Fig.2 Reverse current Vs. Reverse voltage

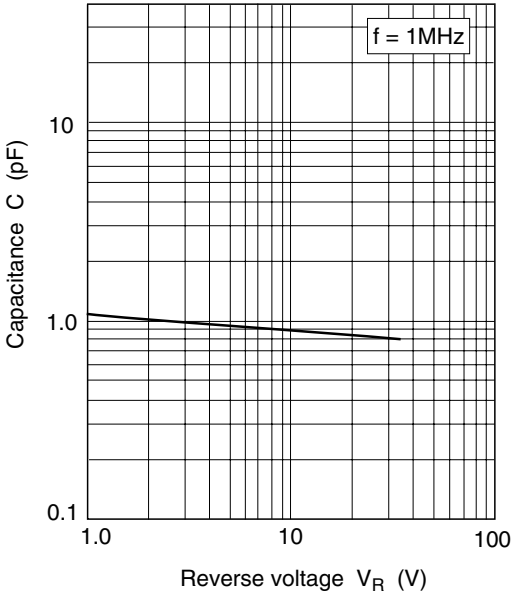
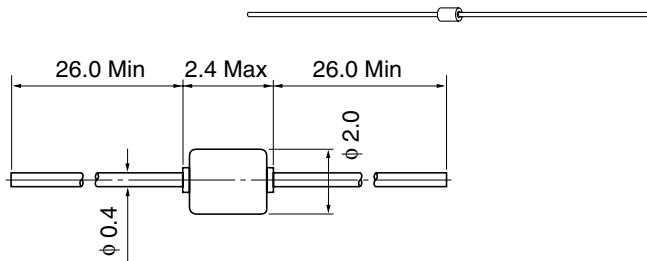


Fig.3 Capacitance Vs. Reverse voltage

## Package Dimensions

Unit: mm



Hitachi Code	MHD
JEDEC	Conforms
EIAJ	—
Mass (reference value)	0.084 g

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